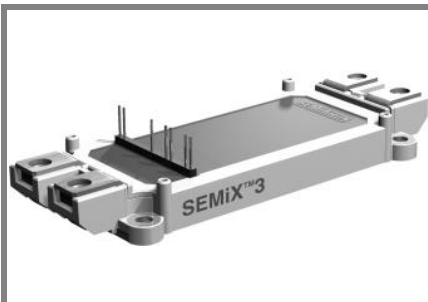


SEMiX 703GB126HD



SEMiX® 3

Trench IGBT Modules

SEMiX 703GB126HD

Preliminary Data

Features

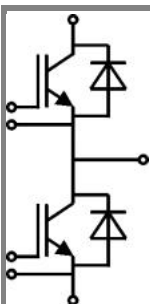
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability

Typical Applications

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperatur limited to $T_C=125^\circ\text{C}$ max.
- Not for new design

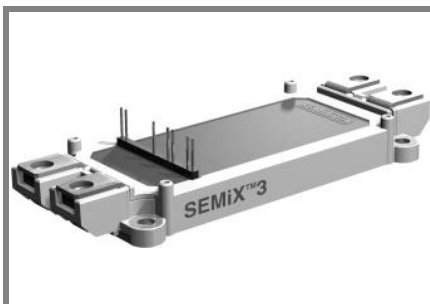


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Absolute Maximum Ratings		T _{case} = 25°C, unless otherwise specified		
Symbol	Conditions		Values	Units
IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	T _j = 150 °C	T _c = 25 °C	650	A
		T _c = 80 °C	450	A
I _{CRM}	I _{CRM} =2xI _{Cnom}		900	A
V _{GES}			± 20	V
t _{psc}	V _{CC} = 600 V; V _{GE} ≤ 20 V; T _j = 125 °C V _{CES} < 1200 V		10	μs
Inverse Diode				
I _F	T _j = 150 °C	T _c = 25 °C	560	A
		T _c = 80 °C	380	A
I _{FRM}	I _{FRM} =2xI _{Fnom}		900	A
I _{FSM}	t _p = 10 ms; sin. T _j = 25 °C		2900	A
Module				
I _{t(RMS)}			600	A
T _{vj}			- 40 ... + 150	°C
T _{stg}			- 40 ... + 125	°C
V _{isol}	AC, 1 min.		4000	V

Characteristics		T _{case} = 25°C, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 18 mA	5	5,8	6,5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES} T _J = 25 °C			0,3	mA
V _{CE0}	T _J = 25 °C T _J = 125 °C		1	1,2	V
			0,9	1,1	V
r _{CE}	V _{GE} = 15 V T _J = 25°C T _J = 125°C		1,6	2,1	mΩ
			2,4	3	mΩ
V _{CE(sat)}	I _{Cnom} = 450 A, V _{GE} = 15 V T _J = 25°C _{chiplev.} T _J = 125°C _{chiplev.}		1,7	2,15	V
			2	2,45	V
C _{ies}	V _{CE} = 25, V _{GE} = 0 V f = 1 MHz		32,3		nF
C _{oes}			1,69		nF
C _{res}			1,46		nF
Q _G	V _{GE} = -8 ... +15V		3600		nC
t _{d(on)}	R _{Gon} = 1,6 Ω	V _{CC} = 600V I _{Cnom} = 450A T _J = 125 °C		310	ns
t _r				60	ns
E _{on}			32	mJ	
t _{d(off)}	R _{Goff} = 1,6 Ω			680	ns
t _f				135	ns
E _{off}			68	mJ	
R _{th(j-c)}	per IGBT			0,061	K/W

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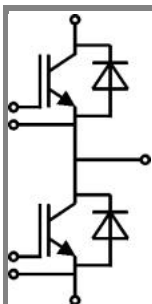
Remarks

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- Not for new design

Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 450 \text{ A}; V_{GE} = 0 \text{ V}$				
	$T_j = 25^\circ\text{C}_{chiplev.}$		1,6	1,8	V
	$T_j = 125^\circ\text{C}_{chiplev.}$		1,6	1,8	V
V_{F0}	$T_j = 25^\circ\text{C}$		1	1,1	V
	$T_j = 125^\circ\text{C}$		0,8	0,9	V
r_F	$T_j = 25^\circ\text{C}$		1,3	1,6	mΩ
	$T_j = 125^\circ\text{C}$		1,8	2	mΩ
I_{RRM}	$I_{Fnom} = 450 \text{ A}$		580		A
Q_{rr}	$di/dt = 8500 \text{ A}/\mu\text{s}$		130		μC
E_{rr}	$V_{GE} = -15 \text{ V}; V_{CC} = 600 \text{ V}$		60		mJ
$R_{th(j-c)D}$	per diode			0,11	K/W
Module					
L_{CE}			20		nH
$R_{CC'+EE'}$	res., terminal-chip	$T_{case} = 25^\circ\text{C}$	0,7		mΩ
		$T_{case} = 125^\circ\text{C}$	1		mΩ
$R_{th(c-s)}$	per module		0,04		K/W
M_s	to heat sink (M5)		3	5	Nm
M_t	to terminals (M6)		2,5	5	Nm
w				300	g
Temperature sensor					
R_{100}	$T_c = 100^\circ\text{C}$ ($R_{25} = 5 \text{ k}\Omega$)		0,493±5%		kΩ
$B_{100/125}$	$R(T) = R_{100} \exp[B_{100/125}(1/T - 1/T_{100})]$ $T[\text{K}]; B$		3550±2%		K

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

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